

N-Channel SiC Power MOSFET

Features

- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitance
- Easy to Parallel and Simple to Drive

Benefits

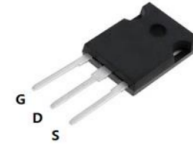
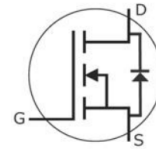
- Higher System Efficiency
- Reduced Cooling Requirements
- Increased Power Density
- Increased System Switching Frequency

Applications

- Solar and UPS inverters
- EV motor drive
- High voltage DC/DC converters
- Switched mode power supplies
- Load switch
- Halogen-free

V_{DS}	=	1200	V
$R_{DS(on)}$	=	16	mΩ
$I_D@25^{\circ}C$	=	120	A

Package



Part Number	Package	Marking
RSM120N120T7	TO-247-3	120N120

Maximum Ratings ($T_c=25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
V_{DSmax}	Drain-Source Voltage	1200	V	$V_{GS}=0V, I_D=100\mu A$	
V_{GSmax}	Gate-Source Voltage	-8/+22	V	Absolute maximum values	
V_{GSop}	Gate-Source Voltage	-4/+18	V	Recommended operational values	
I_D	Continuous Drain Current	120	A	$V_{GS}=18V, T_c=25^{\circ}C$	Fig. 19
		85		$V_{GS}=18V, T_c=100^{\circ}C$	
$I_{D(pulse)}$	Pulsed Drain Current	250	A	Pulse width t_p limited by T_{Jmax}	Fig. 22
P_D	Power Dissipation	375	W	$T_c=25^{\circ}C, T_J=175^{\circ}C$	Fig. 20
T_J, T_{STG}	Operating Junction and Storage Temperature	-55 to +175	$^{\circ}C$		
T_L	Solder Temperature, 1.6mm from case for 10s	260	$^{\circ}C$		
M_d	Mounting Torque, (M3 or 6-32 screw)	1	Nm		
		8.8	lbf-in		

Electrical Characteristics ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	1200	/	/	V	$V_{GS}=0V, I_D=100\mu A$	
$V_{GS(th)}$	Gate Threshold Voltage	1.9	2.6	4.0	V	$V_{DS}=V_{GS}, I_D=23mA$	Fig. 11
		/	1.8	/		$V_{DS}=V_{GS}, I_D=23mA, T_J=175^{\circ}\text{C}$	
I_{DSS}	Zero Gate Voltage Drain Current	/	1	100	μA	$V_{DS}=1200V, V_{GS}=0V$	
I_{GSS+}	Gate-Source Leakage Current	/	10	250	nA	$V_{DS}=0V, V_{GS}=22V$	
I_{GSS-}	Gate-Source Leakage Current	/	10	250	nA	$V_{DS}=0V, V_{GS}=-8V$	
$R_{DS(on)}$	Drain-Source On-State Resistance	/	16	22.3	m Ω	$V_{GS}=18V, I_D=75A$	Fig. 4,5,6
		/	28	/		$V_{GS}=18V, I_D=75A, T_J=175^{\circ}\text{C}$	
g_{fs}	Transconductance	/	41.4	/	S	$V_{DS}=20V, I_{DS}=75A$	Fig. 7
		/	36.5	/		$V_{DS}=20V, I_{DS}=75A, T_J=175^{\circ}\text{C}$	
C_{iss}	Input Capacitance	/	4817	/	pF	$V_{GS}=0V$	Fig. 17,18
C_{oss}	Output Capacitance	/	207	/		$V_{DS}=1000V$	
C_{rss}	Reverse Transfer Capacitance	/	45	/		$f=1MHz$	
E_{oss}	C_{oss} Stored Energy	/	104	/	μJ	$V_{AC}=25mV$	Fig. 16
E_{ON}	Turn-On Switching Energy	/	2.1	/	mJ	$V_{DS}=800V, V_{GS}=-4V/18V$	
E_{OFF}	Turn-Off Switching Energy	/	1.6	/		$I_D=30A, R_{G(ext)}=2.5\Omega, L=100\mu H$	
$t_{d(on)}$	Turn-On Delay Time	/	150	/	ns	$V_{DS}=800V, V_{GS}=-4V/18V, I_D=30A$ $R_{G(ext)}=2.5\Omega, R_L=20\Omega$	
t_r	Rise Time	/	38	/			
$t_{d(off)}$	Turn-Off Delay Time	/	108	/			
t_f	Fall Time	/	35	/			
$R_{G(int)}$	Internal Gate Resistance	/	4.5	/	Ω	$f=1MHz, V_{AC}=25mV$	
Q_{GS}	Gate to Source Charge	/	66	/	nC	$V_{DS}=800V$	Fig. 12
Q_{GD}	Gate to Drain Charge	/	48	/		$V_{GS}=-4V/18V$	
Q_G	Total Gate Charge	/	269	/		$I_D=30A$	

Reverse Diode Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_{SD}	Diode Forward Voltage	4.2	/	V	$V_{GS}=-4V, I_{SD}=37.5A, T_J=25^{\circ}\text{C}$	Fig. 8,9,10
		3.9	/		$V_{GS}=-4V, I_{SD}=37.5A, T_J=175^{\circ}\text{C}$	
I_S	Continuous Diode Forward Current	/	120	A	$T_C=25^{\circ}\text{C}$	
t_{rr}	Reverse Recover Time	54	/	ns	$V_R=800V, I_{SD}=30A$	
Q_{rr}	Reverse Recovery Charge	630	/	nC		
I_{rrm}	Peak Reverse Recovery Current	19	/	A		

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.23	/	$^{\circ}\text{C/W}$		Fig. 21
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	/	40			

RATING AND CHARACTERISTICS CURVES (RSM120N120T7)

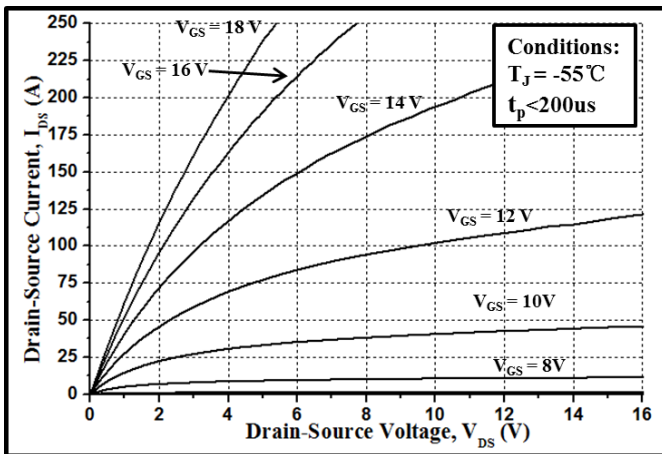


Figure 1. Output Characteristics $T_j = -55^\circ\text{C}$

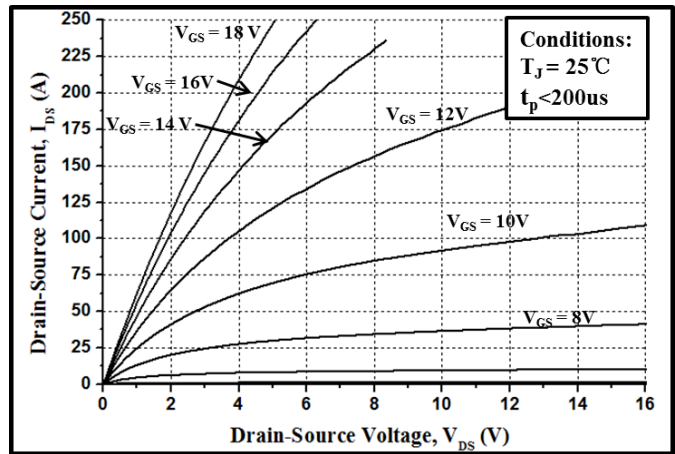


Figure 2. Output Characteristics $T_j = 25^\circ\text{C}$

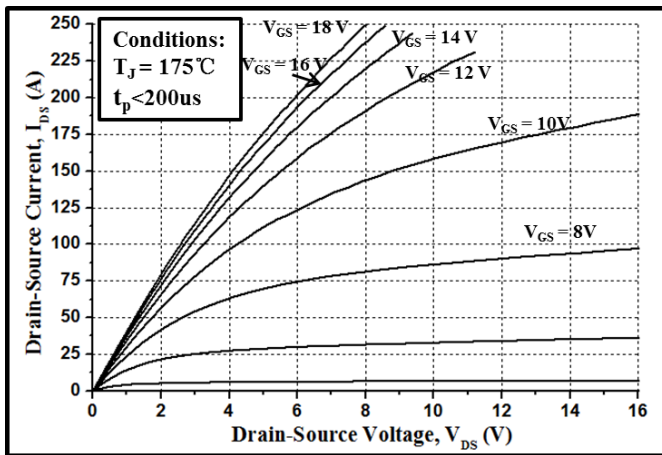


Figure 3. Output Characteristics $T_j = 175^\circ\text{C}$

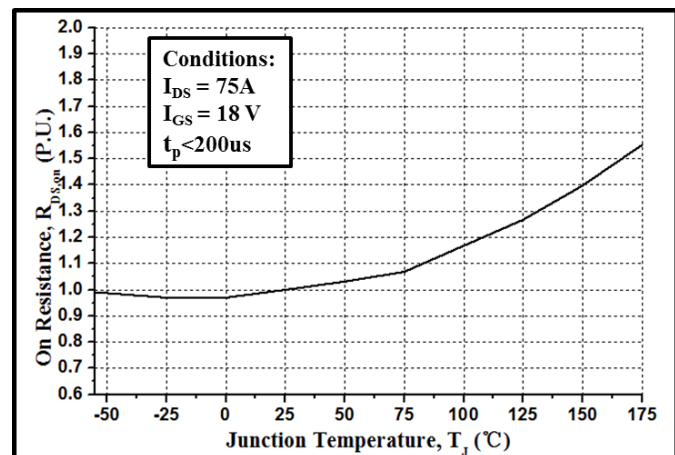


Figure 4. Normalized On-Resistance vs. Temperature

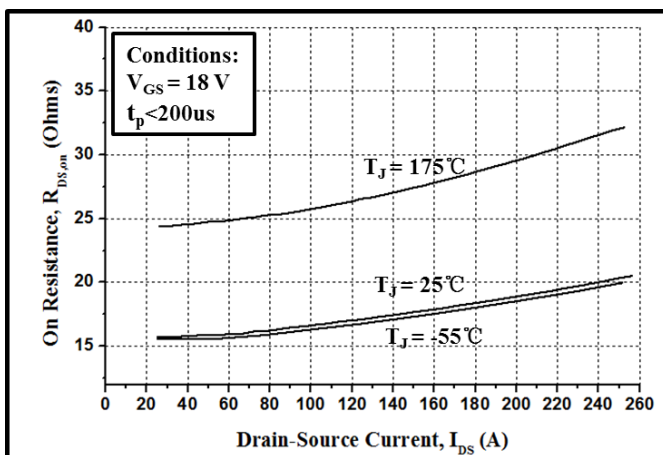


Figure 5. On-Resistance vs. Drain Current
For Various Temperatures

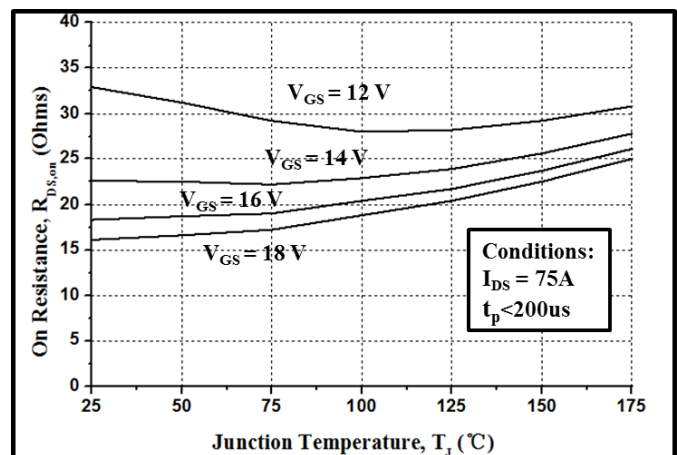


Figure 6. On-Resistance vs. Temperature
For Various Gate Voltage

RATING AND CHARACTERISTICS CURVES (RSM120N120T7)

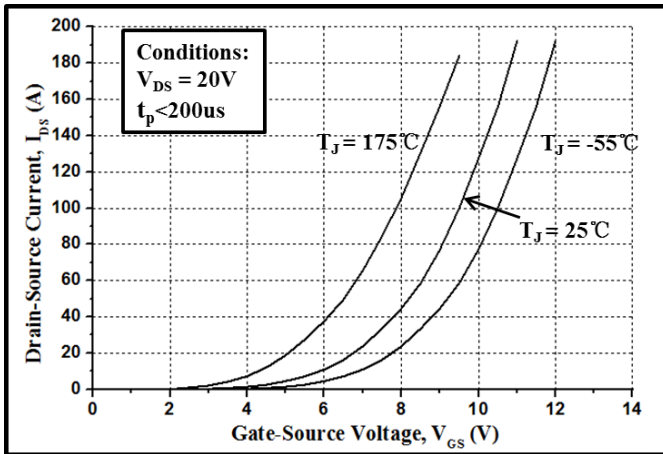


Figure 7. Transfer Characteristic for Various Junction Temperatures

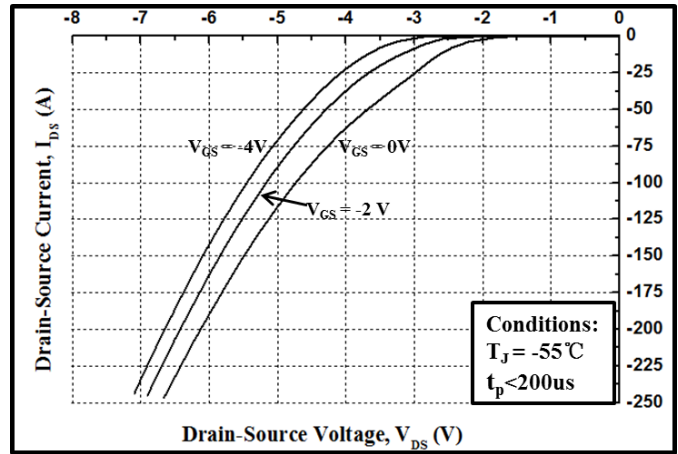


Figure 8. Body Diode Characteristic at -55°C

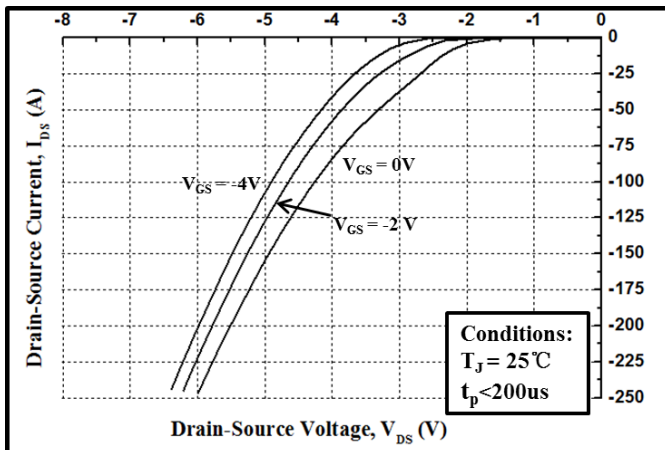


Figure 9. Body Diode Characteristic at 25°C

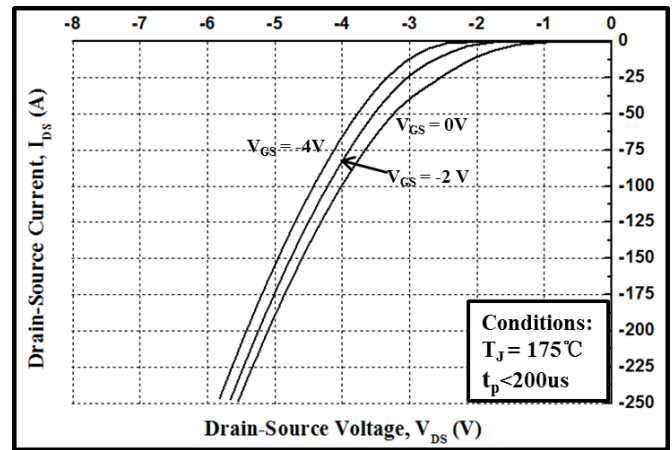


Figure 10. Body Diode Characteristic at 175°C

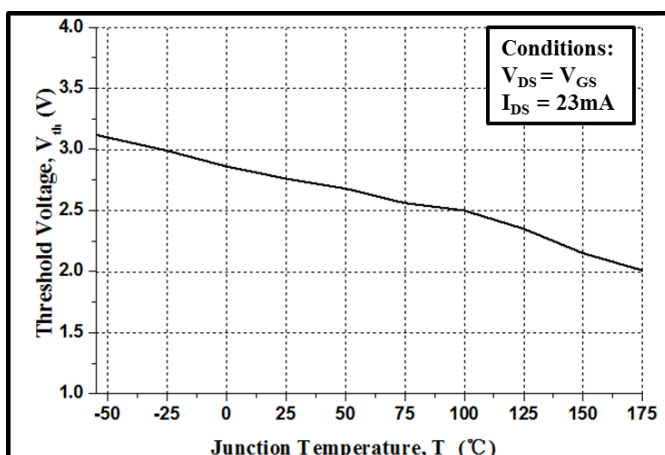


Figure 11. Threshold Voltage vs. Temperature

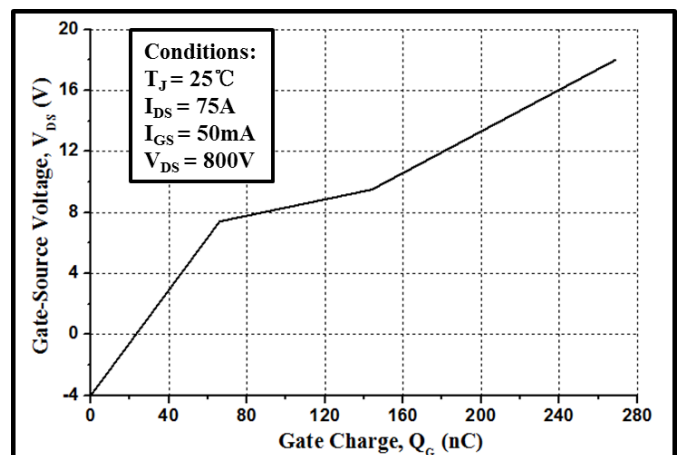


Figure 12. Gate Charge Characteristics

RATING AND CHARACTERISTICS CURVES (RSM120N120T7)

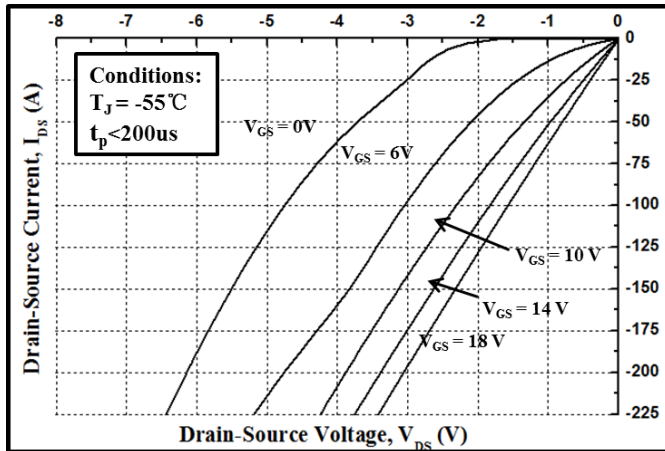


Figure 13. 3rd Quadrant Characteristic at -55°C

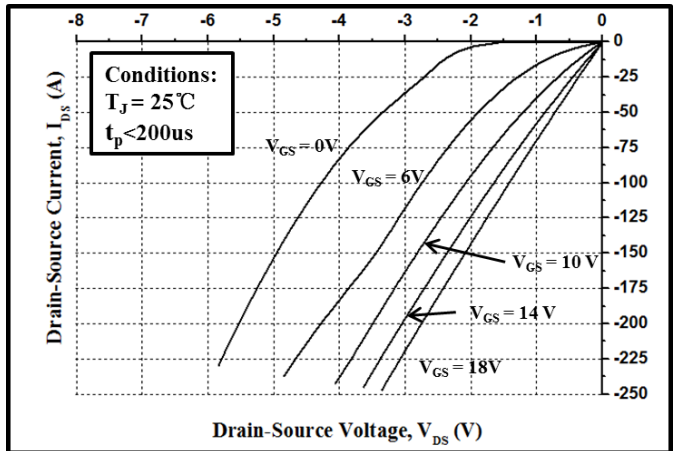


Figure 14. 3rd Quadrant Characteristic at 25°C

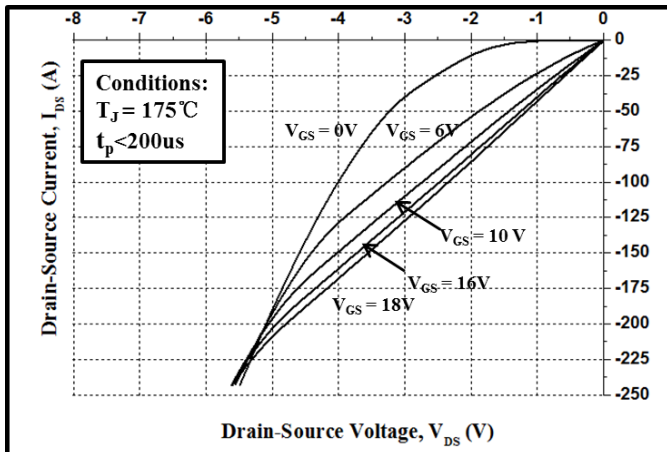


Figure 15. 3rd Quadrant Characteristic at 175°C

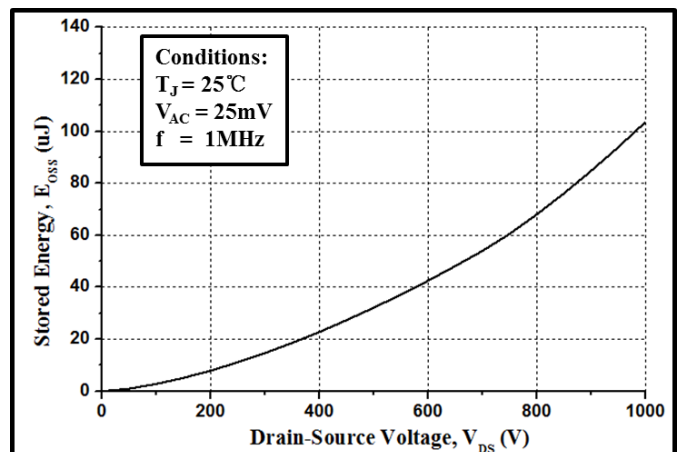


Figure 16. Output Capacitor Stored Energy

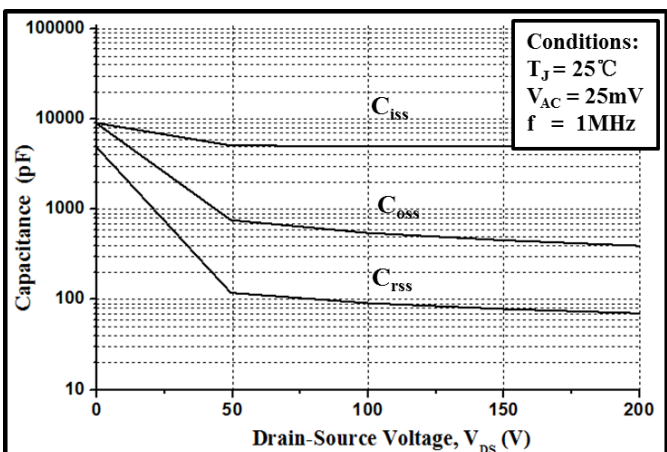


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

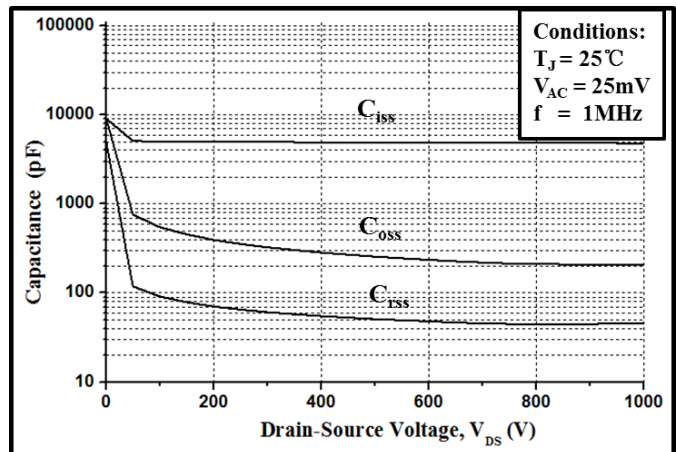


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1000V)

RATING AND CHARACTERISTICS CURVES (RSM120N120T7)

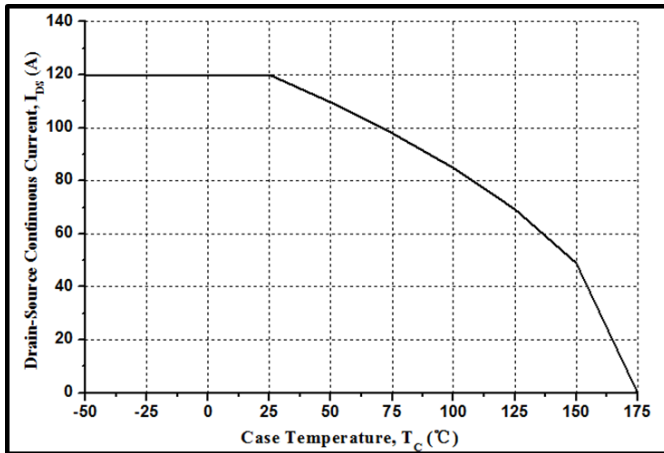


Figure 19. Continuous Drain Current vs. Case Temperature

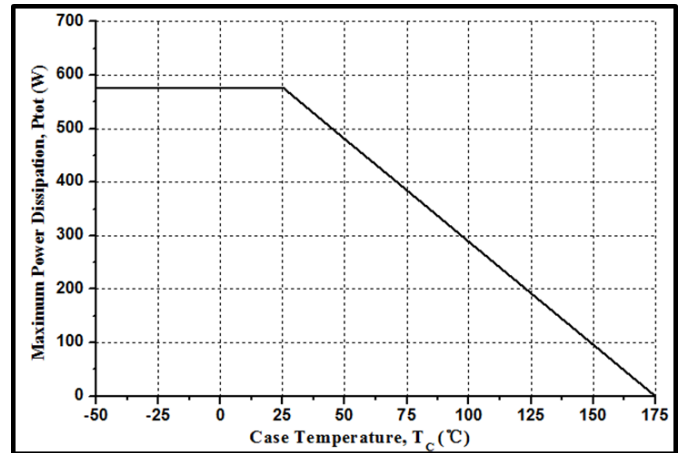


Figure 20. Maximum Power Dissipation vs. Case Temperature

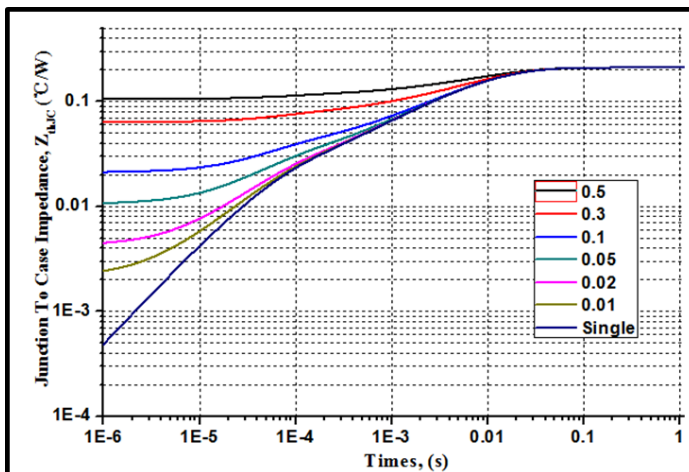


Figure 21. Transient Thermal Impedance (Junction - Case)

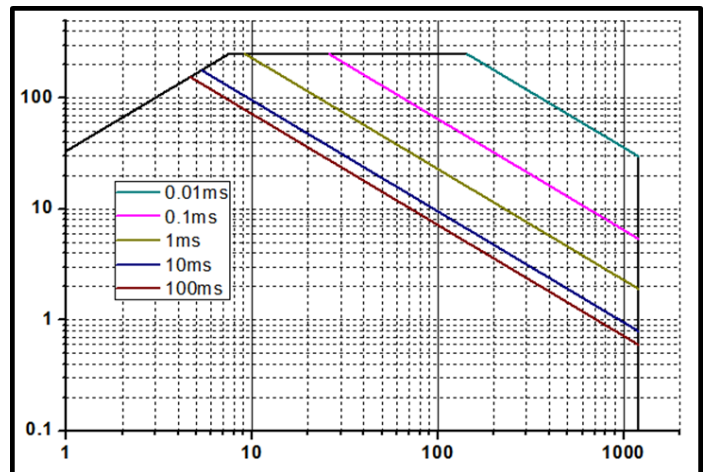


Figure 22. Safe Operating Area

Test Circuit Schematic

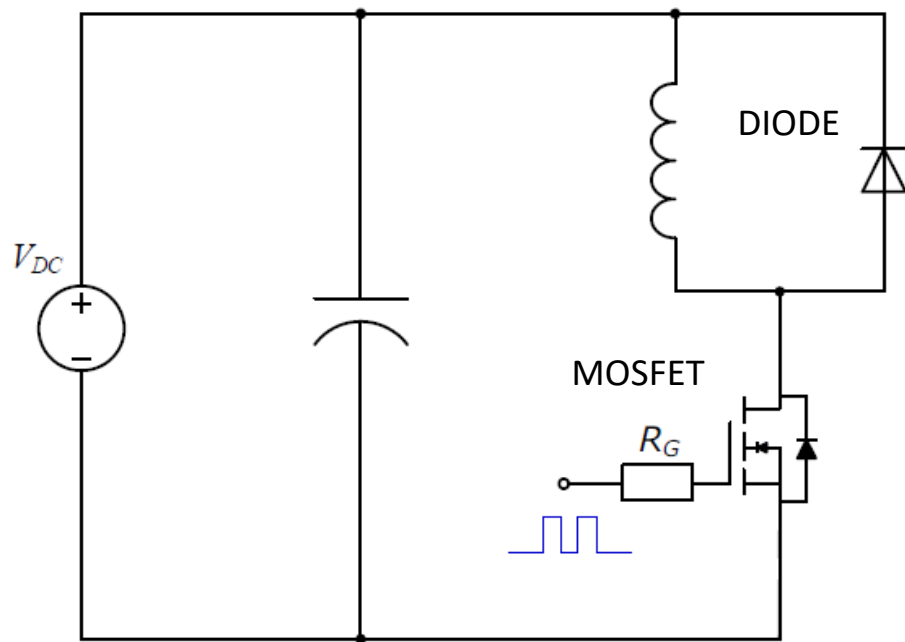
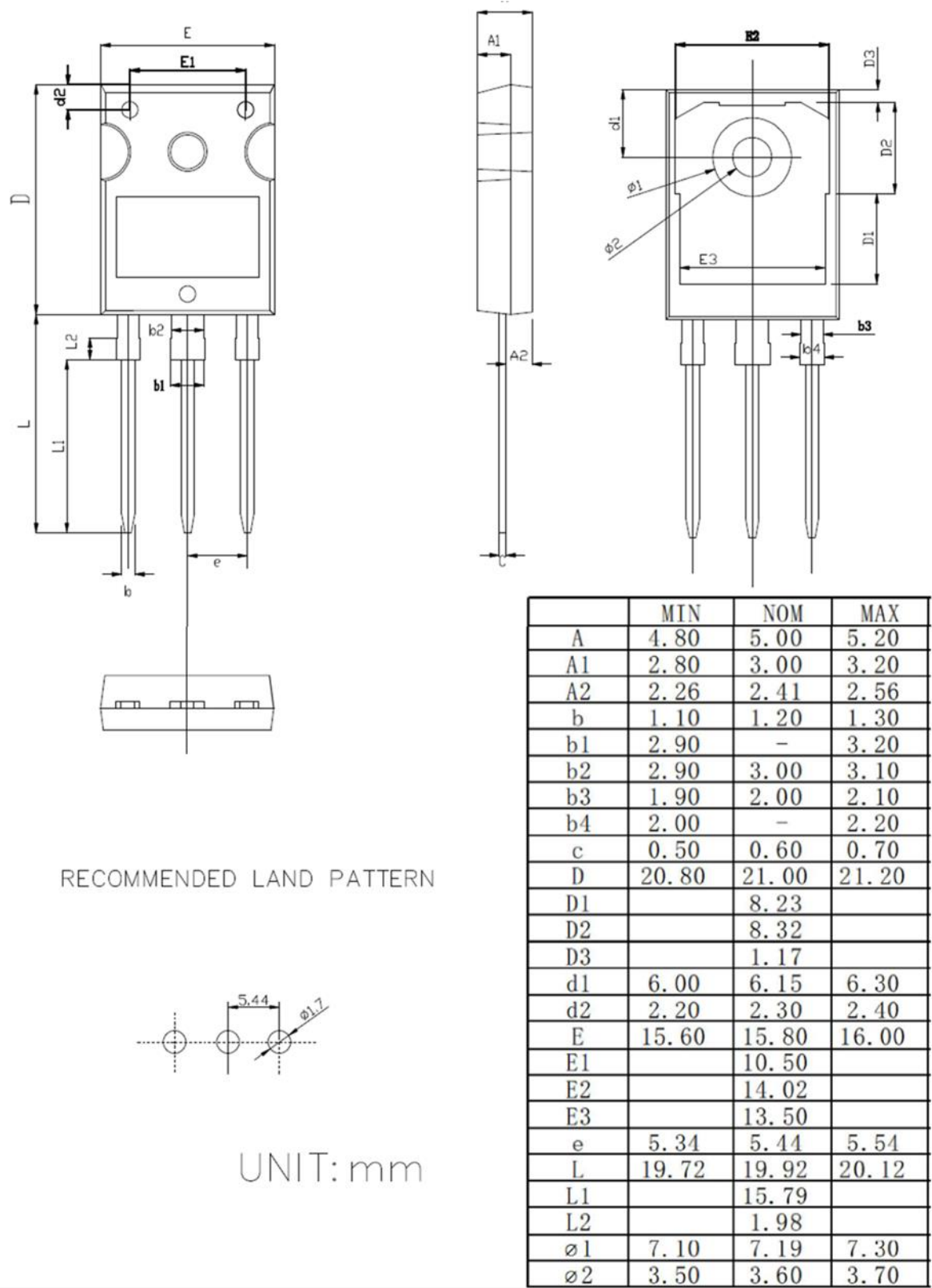


Figure 23. Clamped Inductive Switching
Waveform Test Circuit

Package Dimensions



DISCLAIMER NOTICE

Rectron Inc reserves the right to make changes without notice to any product specification herein, to make corrections, modifications, enhancements or other changes. Rectron Inc or anyone on its behalf assumes no responsibility or liability for any errors or inaccuracies. Data sheet specifications and its information contained are intended to provide a product description only. "Typical" parameters which may be included on RECTRON data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. Rectron Inc does not assume any liability arising out of the application or use of any product or circuit.

Rectron products are not designed, intended or authorized for use in medical, life-saving implant or other applications intended for life-sustaining or other related applications where a failure or malfunction of component or circuitry may directly or indirectly cause injury or threaten a life without expressed written approval of Rectron Inc. Customers using or selling Rectron components for use in such applications do so at their own risk and shall agree to fully indemnify Rectron Inc and its subsidiaries harmless against all claims, damages and expenditures.